MH188 Hall-effect sensor is a temperature stable, stress-resistant sensor. Superior high-temperature performance is made possible through a dynamic offset cancellation that utilizes chopper-stabilization. This method reduces the offset voltage normally caused by device over molding, temperature dependencies, and thermal stress.

MH188 includes the following on a single silicon chip: voltage regulator, Hall voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, Advanced DMOS wafer fabrication processing is used to take advantage of low-voltage requirements, component matching, very low input-offset errors, and small component geometries.

This device requires the presence of both south and north polarity magnetic fields for operation. In the presence of a south polarity field of sufficient strength, the device output sensor on, and only switches off when a north polarity field of sufficient strength is present.

Packages is Halogen Free standard and which have been verified by third party lab.

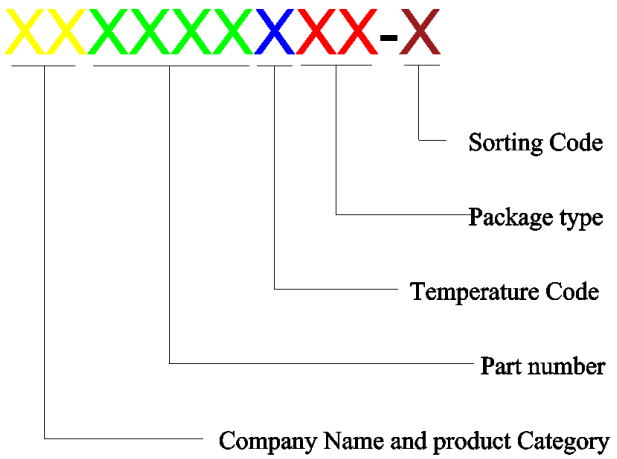
Features and Benefits

- DMOS Hall IC Technology.
- Reverse bias protection on power supply pin.
- Chopper stabilized amplifier stage.
- Optimized for BLDC motor applications.
- Reliable and low shifting on high Temp condition.
- Good ESD Protection.
- 100% tested at 125 ℃ for K.
- Custom sensitivity / Temperature selection are available.
- RoHS compliant 2011/65/EU and Halogen Free

Applications

- High temperature Fan motor
- 3 phase BLDC motor application
- Speed sensing
- Position sensing
- Current sensing
- Revolution counting
- Solid-State Switch
- Linear Position Detection
- Angular Position Detection
- Proximity Detection
- High ESD Capability

Ordering Information



Company Name and Product Category

MH:MST Hall Effect/MP:MST Power IC

Part number

181,182,183,184,185,248,249,276,477,381,381F,381R,382…..

If part # is just 3 digits, the forth digit will be omitted.

Temperature range

E: 85 ℃, I: 105 ℃, K: 125 ℃, L: 150 ℃

Package type

UA:TO-92S,VK:TO-92S(4pin),VF:TO-92S(5pin),SO:SOT-23,
SQ:QFN-3,ST:TSOT-23,SN:SOT-553,SF:SOT-89(5pin),
SS:TSOT-26,SD:DFN-6

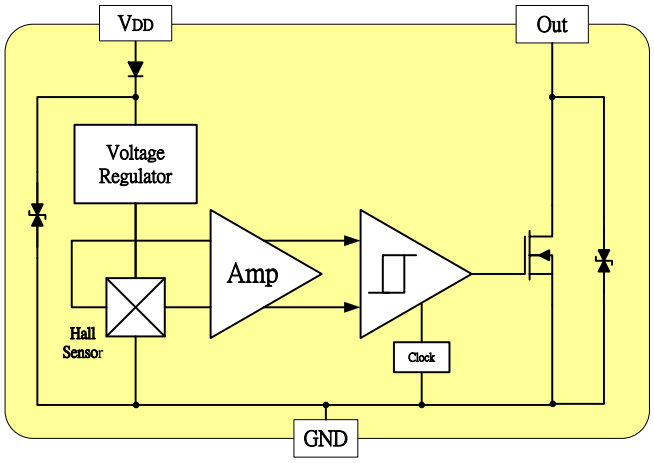
Sorting

α,β,Blank…..

Part No.	Temperature Suffix	Package Type
MH188KUA	K (-40°C to + 125°C)	UA (TO-92S)
MH188KSO	K (-40°C to + 125°C)	SO (SOT-23)
MH188EUA	E (-40°C to + 85°C)	UA (TO-92S)
MH188ESO	E (-40°C to + 85°C)	SO (SOT-23)
MH188ESD	E(-40°C to +85°C)	SD (DFN2*2-6L)

KUA spec is using in industrial and automotive application. Special Hot Testing is utilized.

Functional Diagram



Absolute Maximum Ratings *At (Ta=25℃)*

Characteristics		Values	Unit
Supply voltage, (V_{DD})		28	V
Output Voltage,(V_{out})		28	V
Reverse voltage, (V_{DD})		-28/-0.3	V
Output current, ($Iout$)		50	mA
Operating Temperature Range, (Ta)	"E" version	-40 to +85	℃
	"K" version	-40 to +125	℃
Storage temperature range, (Ts)		-65 to +150	℃
Maximum Junction Temp,(Tj)		150	℃
Thermal Resistance	(θ_{ja}) UA / SO	206 / 543	℃/W
	(θ_{jc}) UA / SO	148 / 410	℃/W
Package Power Dissipation, (P_D) UA / SO		606 / 230	mW

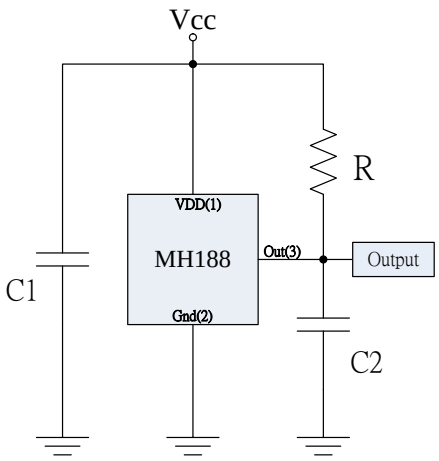
***Note**: Do not apply reverse voltage to* V_{DD} and V_{OUT} *Pin, It may be caused for Miss function or damaged device.*

Electrical Specifications

DC Operating Parameters ： T_A=+25℃, V_{DD}=12V

Parameters	Test Conditions	Min	Typ	Max	Units
Supply Voltage,(V_{DD})	Operating	2.5		26.0	V
Supply Current,(I_{DD})	B<BOP			5.0	mA
Output Saturation Voltage, (V_{sat})	Iout=20mA,B>BOP			400.0	mV
Output Leakage Current, (I_{off})	IOFF B<BRP, VOUT = 12V			10.0	uA
Internal Oscillator Chopper Frequency,(f_{OSC})			69		kHz
Output Rise Time, (T_R)	R_L=1.1KΩ, CL =20pF		0.04	0.45	uS
Output Fall Time, (T_F)	R_L=820Ω; CL =20pF		0.18	0.45	uS
Electro-Static Discharge	HBM	4			KV
Operate Point,(B_{OP})	UA(SO)	5(-25)		25(-5)	Gauss
Release Point,(B_{RP})	UA(SO)	-25(5)		-5(25)	Gauss
Hysteresis,(B_{HYS})			30		Gauss

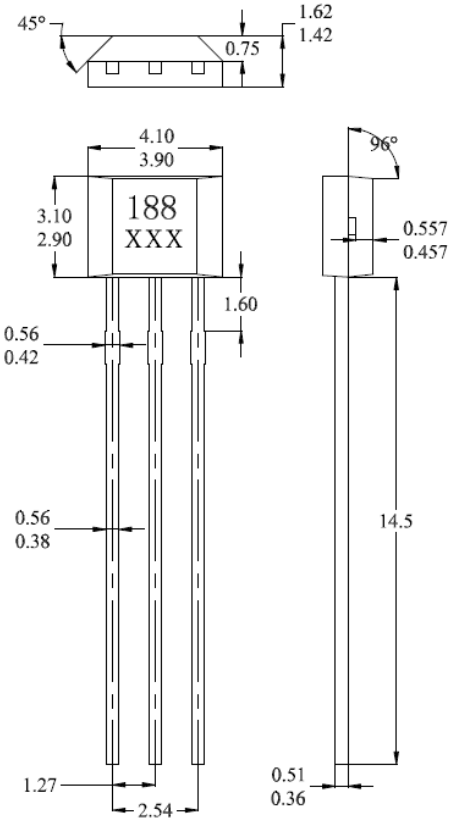
Typical application circuit



R：1KΩ
C1：10nF
C2：1nF

Sensor Location, Package Dimension and Marking

UA Package



NOTES:

1.Controlling dimension: mm

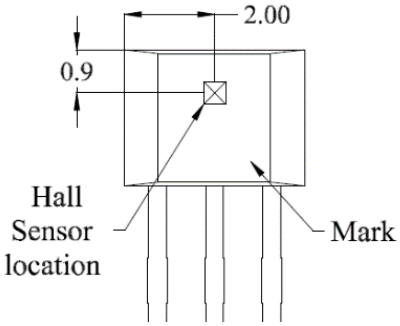
2.Leads must be free of flash and plating voids

3.Do not bend leads within 1 mm of lead to package interface.

4.PINOUT:

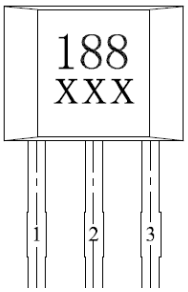
Pin 1	VCC
Pin 2	GND
Pin 3	Output

Hall Chip location



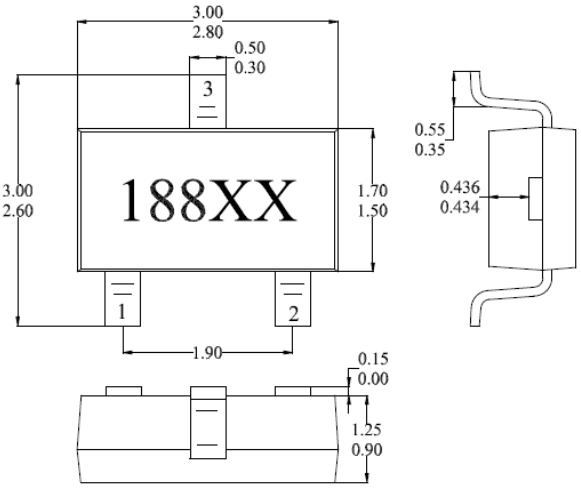
Output Pin Assignment

(Top view)



Package (SOT-23)

(Top View)

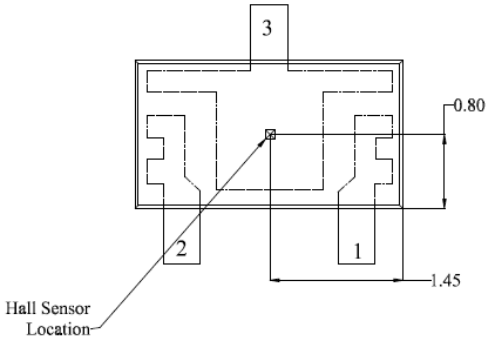


NOTES:

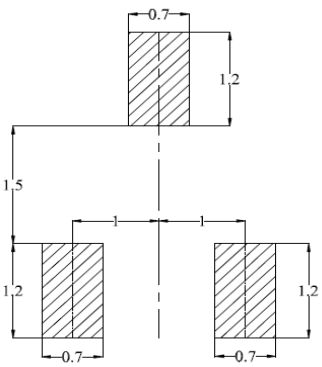
1. PINOUT (See Top View at left :)
   Pin 1 V_{DD}
   Pin 2 Output
   Pin 3 GND
2. Controlling dimension: mm
3. Lead thickness after solder plating will be 0.254mm maximum

Hall Plate Chip Location

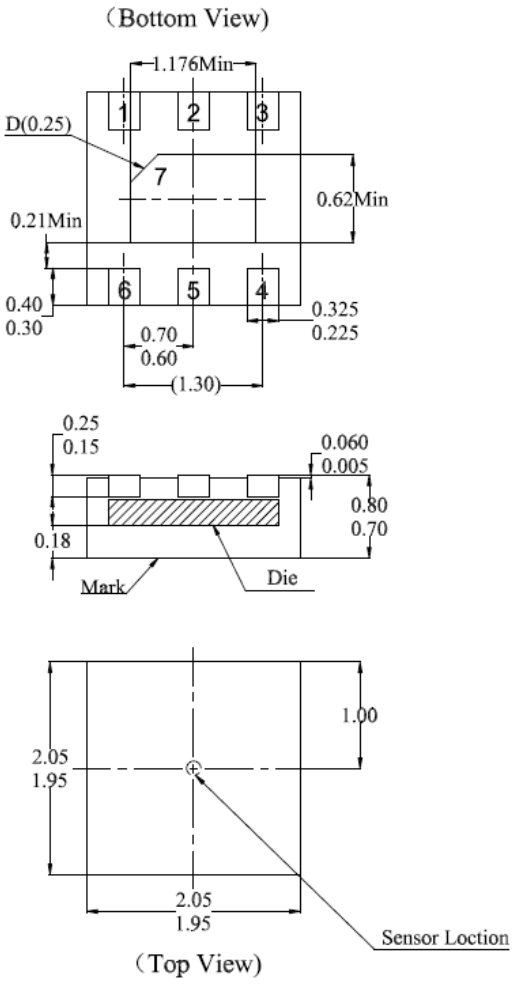
(Bottom view)



(For reference only)Land Pattern



SD Package



NOTES:

1. Controlling dimension: mm
2. Leads must be free of flash and plating voids
3. Lead thickness after solder plating will be 0.254mm maximum
4. PINOUT:

Pin No.	Pin Name	Function
1	V_{DD}	Power Supply
2	N.C	N.C
3	V_{OUT}	Output
4	N.C	N.C
5	V_{SS}	Ground
6	N.C	N.C
7	N.C	N.C

5. （For reference only）Land pattern